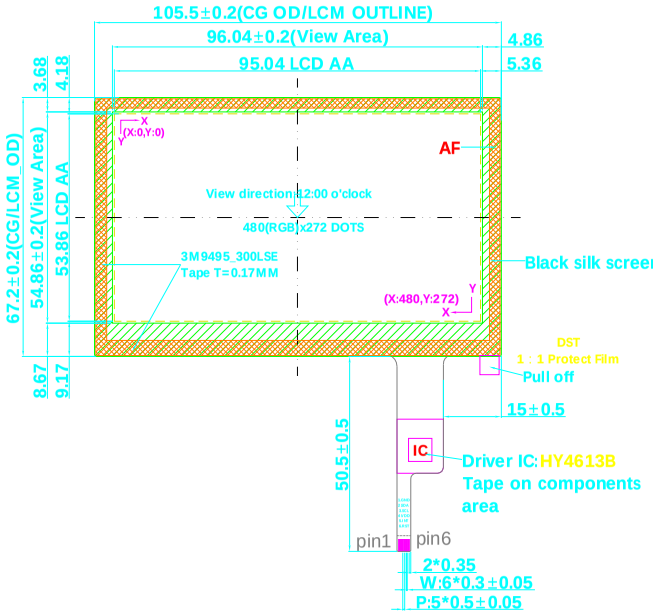
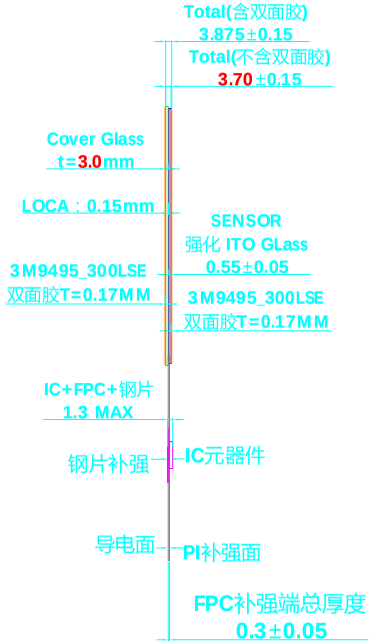
Version	Item	DWG	Checked	Date
VER. 1	Initial version			2017. 02. 23

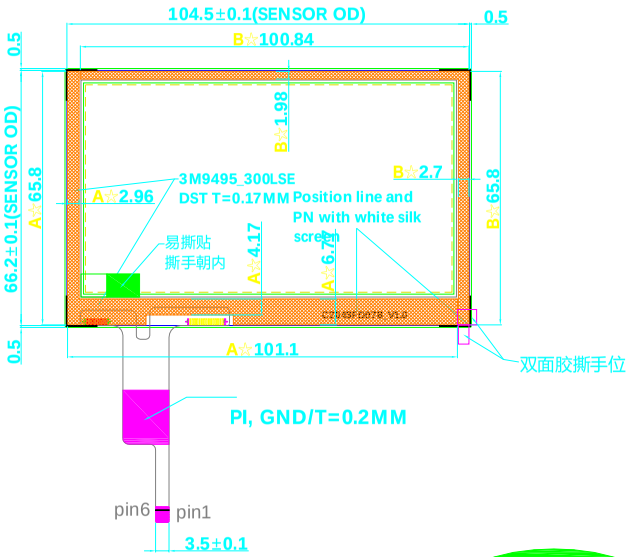
Front



Side



Back



RoHS

Parameters：

1. Structure: G+G：Cover Glass+LOCA+ITO GLASS+FPC,Cover Glas s 3.0mm，LOCA:0.15mm,ITO GLASS:0.55mm, Total Thickness：3.875±0.15mm（incl. DST）;
2. IC：HY4613B(COF),5 points, Channel：15*9; Operation Vol.:3.3V，FPC Connector: Standard IIC, IO Vol.：2.8V; IIC Mac：0X70;
3. Transparence:≥85%; TP Resolution：X:480,Y:272;
4. Operation Condition: -20℃~+70℃,≤90%RH; Storage Condition: -30℃~+80℃，≤90%RH;
5. Hardness：≥6H（Pencil testing）;
6. Cover Glass：Tempered glass (AGC); RoHS Compliance;
7. Tolerance:±0.2;

IC元器件:HY4613B

PIN	定义
1	GND
2	SDA
3	SCL
4	VDD
5	INT
6	RST

		Tolerance	+/-0.2
PN		投 影	
	CTP	Unit	M M
DWG		Scale	1 : 1
Checked		Date	2017. 02. 23